



SOD-57, SOD-64, DO-35, and DO-41 Trim and Form Process Recommendations

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SCOPE:

SOD-57 AND SOD-64 SINTERGLASS PACKAGE

DO-35 AND DO-41 GLASS DIODE PACKAGE

RECOMMENDATIONS FOR THE TRIM AND FORM PROCESS

Vishay’s SOD-57, SOD-64, DO-35, and DO-41 are hermetically sealed diodes with glass packages. Careful handling of the devices during the trim and form process is very important to avoid changing or damaging the electrical and mechanical characteristics of the diodes.

Vishay recommends the following guidelines be followed during the trim and form process for leaded glass diodes:

Cutting / trimming of lead wires:

- The glass body must be free from any mechanical stress during the trimming process
- To avoid push / pull forces on the glass body, do not attempt to cut or trim both lead wires at the same time

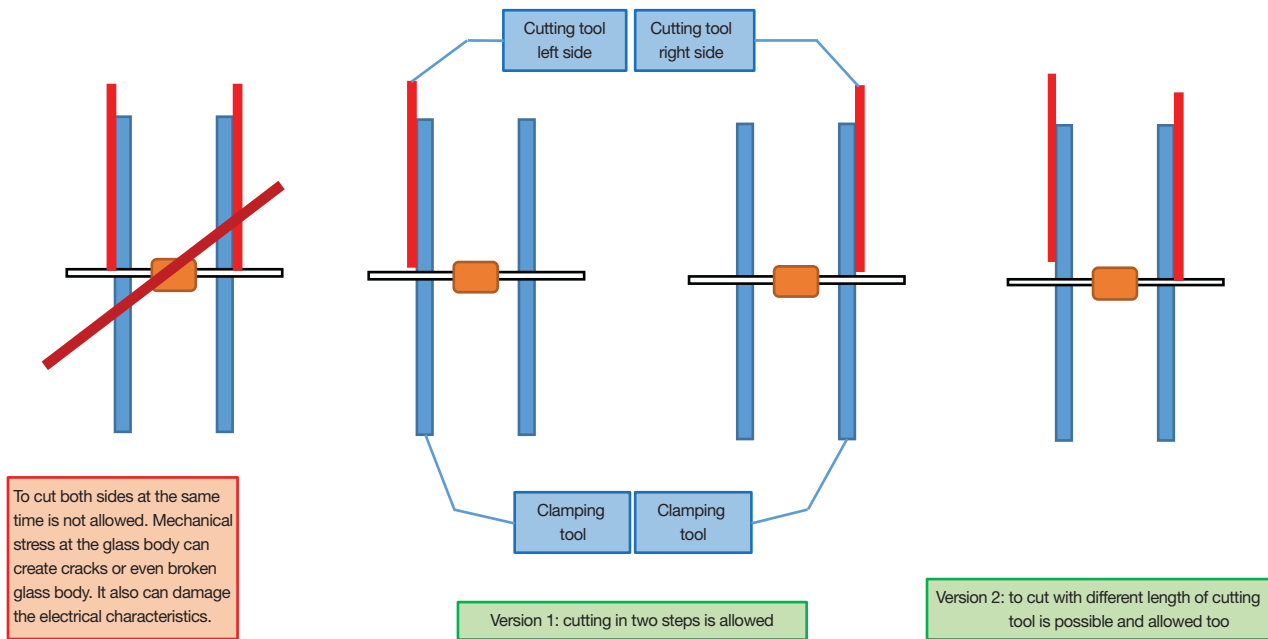


Fig. 1 - Lead Cutting / Trimming Process

APPLICATION NOTE

SOD-57, SOD-64, DO-35, and DO-41 Trim and Form Process Recommendations

Forming process:

- The glass body must be free from all mechanical stress during the forming process
- To avoid push / pull forces on the glass body, diodes must be fixed using a special tool with a minimum clamping force of 2.5 kg applied
- Small clamping imprints must be visible at the lead wires to confirm a good clamping
- The distance of the glass body to the bending position must be > 1.5 mm

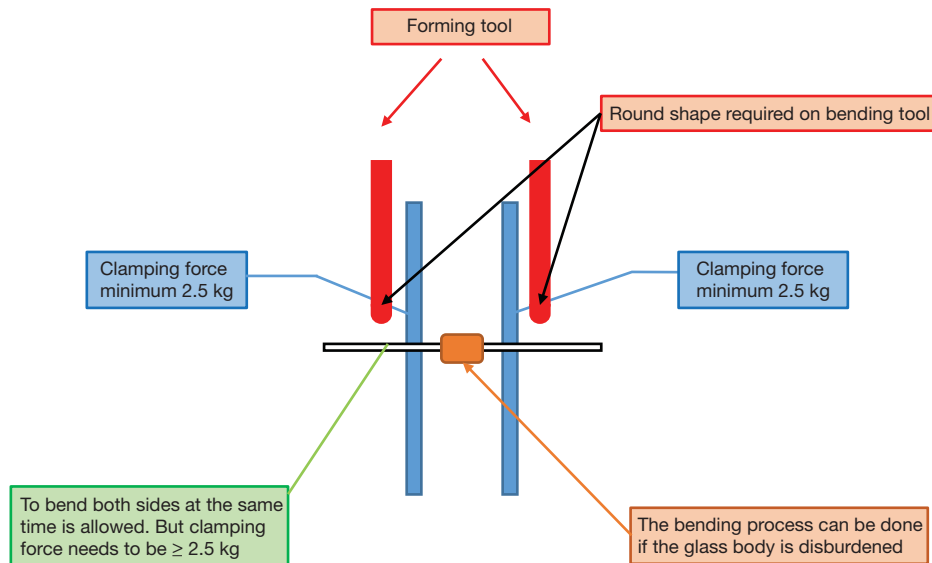


Fig. 2 - Lead Bending / Forming Process